Claims

1. A system for unloading integrated circuit (IC) units, the system comprising:
a first unloading station arranged to unload the IC units to JEDEC IC tray;
a second unloading station arranged to unload the IC units to wafer rings;
a delivery system arranged to deposit said IC units in the first unloading station the or second unloading station, and;
a control system for selecting which unloading station each IC unit is to be deposited,
wherein the control system is arranged to make the selection based upon predetermined criteria, said predetermined criteria comprising type of the IC units, type of end use processing equipment, and industry in which the IC units are applied.

2. The system according to claim 1, further including an inspection system wherein the delivery system is arranged to pass the IC units through the inspection system prior to being deposited in the first or second unloading station.

3. The system according to claim 2, wherein the inspection system is arranged to identify IC units to be rejected with the delivery system arranged to place rejected IC units in a reject bin prior to the unloading stations.

4. A method for unloading integrated circuit (IC) units to a first unloading station or a second unloading station, the method comprising the steps of:
selecting which unloading station each IC unit is to be deposited in based upon predetermined criteria, said predetermined criteria comprising type of the IC units, type of end use processing equipment, and industry in which the IC units are applied;
depositing said IC units in the selected unloading station;
unloading IC units deposited in the first unloading station to JEDEC IC trays; and
unloading IC units deposited in the second unloading station to wafer rings.

5. The system according to claim 4, further including the step of inspecting the IC units prior to being depositing step.

6. The method according to claim 5, wherein the inspecting step includes identifying IC units to be rejected;
further including the step of placing the rejected IC units in a reject bin prior to the depositing step.